/ Descriptions

SOD-523

Silicon Diode in a SOD-523 Plastic Package.

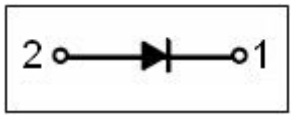
/ Features

Fast switching diodes,HF Product.

/ Applications

Small signal diode.

/ Equivalent Circuit

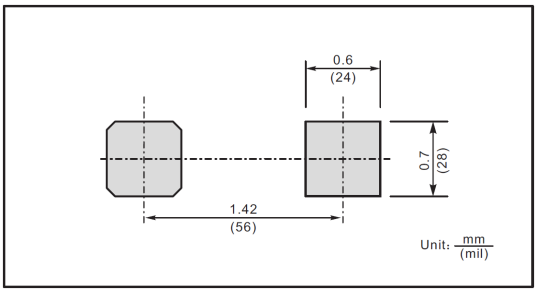


/ Pinning



PIN1:Cathode PIN2:Anode

The recommended mounting pad size



/ Marking

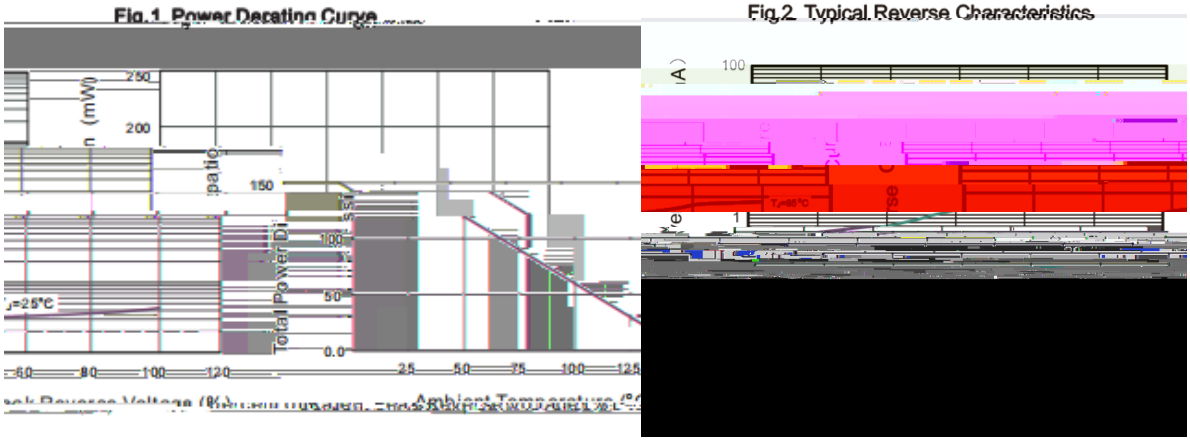
Marking	T4

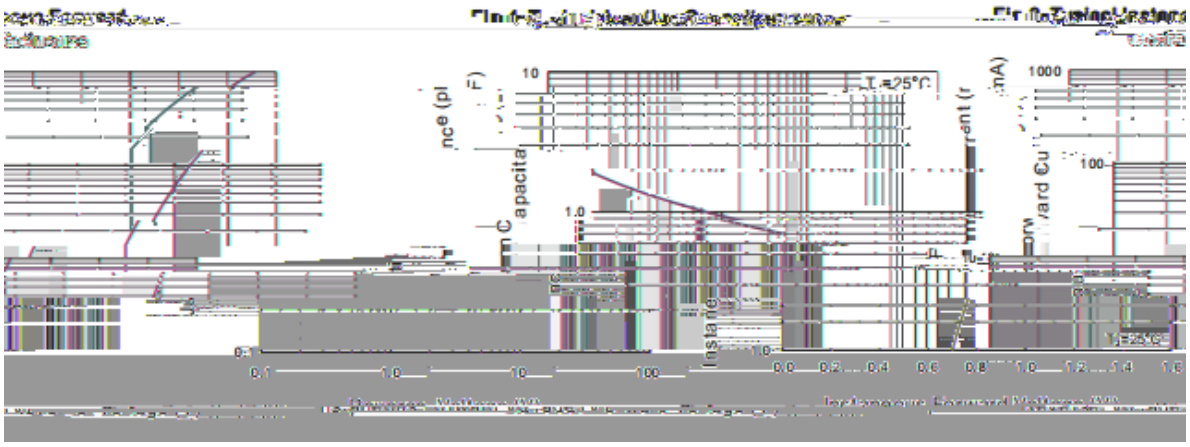
Parameter	Symbol	Rating	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	V
Maximum RMS voltage	V_{RMS}	75	V
Continuous Forward Current	I_F	150	mA
Non-reptitive Peak Forward Surge Current	I_{FSM} t=1ms	0.8	A
Power Dissipation	P_{tot}	150	mW
Junction Temperature	T_j	-55 150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Breakdown Voltage	$V_{(BR)R}$	I_R=1μA	75			V
		I_F=1mA			0.715	V
					0.855	

V V

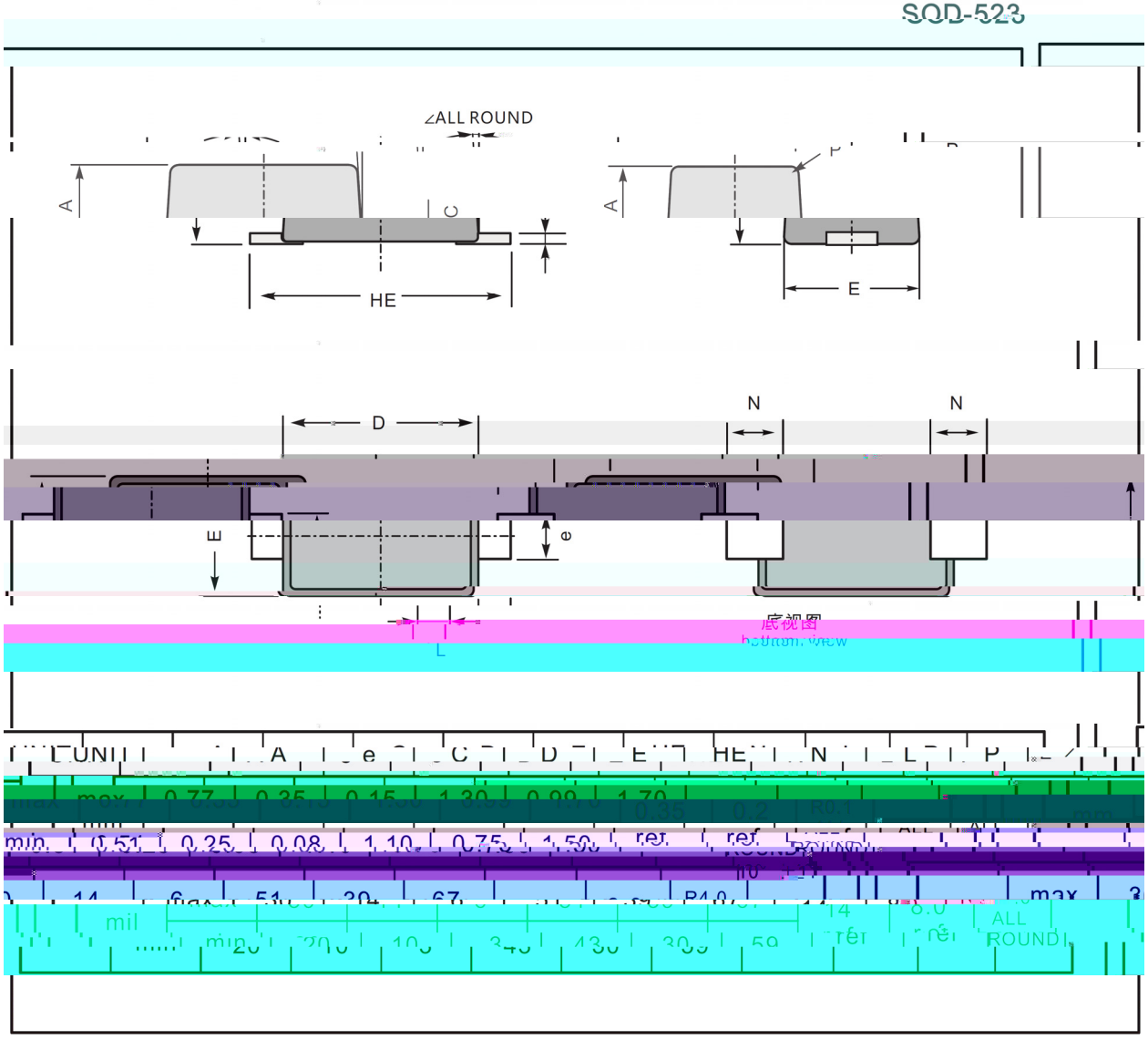
/ Electrical Characteristic Curve





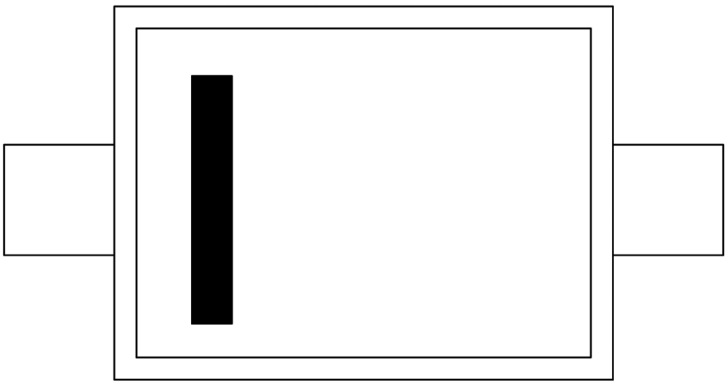
/ Package Dimensions

SOD-523



UNIT	A	e	C	D	E	HE	N	L	P
max	0.77	0.35	0.15	1.30	0.90	1.70		0.35	0.2
min	0.51	0.25	0.08	1.10	0.75	1.50	ref.	ref.	
mil	max	51	30	67				14	8.0
	min	20	10	43	30	59	ref.	ref.	ALL ROUND

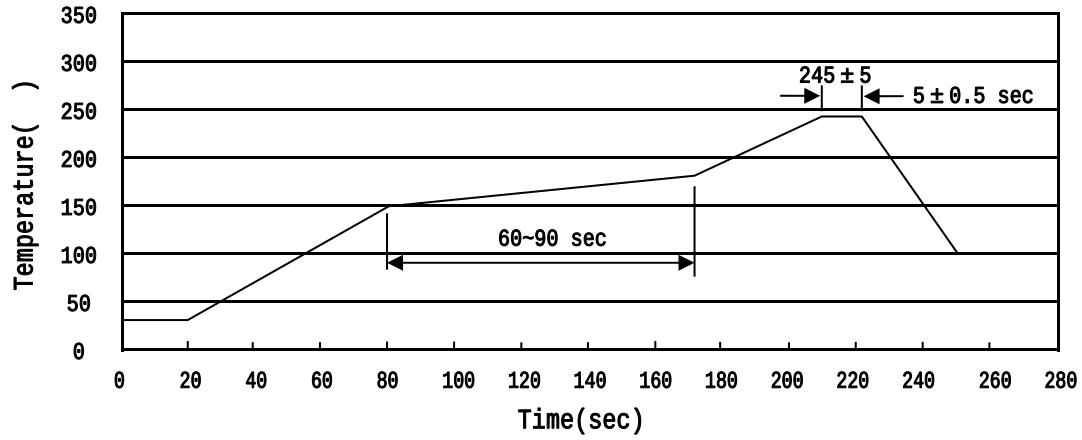
/ Marking Instructions



T4

T563.5ye

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



						Note:	
1		150	180		60	90sec;	1.Preheating:150~180 , Time:60~90sec.
2		245±5				5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.
3				2	10	/sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension		(unit mm³)
SOD-523	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205

/ Notices